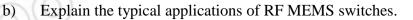
B.E. Seventh Semester (Electronics & Telecommunication / Electronics & Communication Engineering) (C.B.S.) Elective - I : Micro Electromechanical Systems & System on Chip (MEMS)

P. Pages : 2 Time : Three Ho	burs $* 0 1 0 2 *$	050	NKT/KS/17/7456 Max. Marks : 80
Notes : 1 2 3 4 5 6 7 8 9 1	 Solve Question 1 OR Questions No. 2. Solve Question 3 OR Questions No. 4. Solve Question 5 OR Questions No. 6. Solve Question 7 OR Questions No. 8. Solve Question 9 OR Questions No. 10. Solve Question 11 OR Questions No. 12. Due credit will be given to neatness and ad 	-	cetches.
1. a) Wha	tt is miniaturization? State benefits of miniaturiz	zation.	6
b) Expl	lain Accelerometer in MEMS & give its applica	ation.	7
2. a) Diffe	erentiate between microelectronics & microsyst	tems.	7
b) Expl	lain Bio-MEMS in detail.		6
3. a) Expl	lain Bulk micromachining techniques in detail.		
b) Diffe	erentiate between wet etching & dry etching pro	ocess.	
4. a) Expl	lain device fabrication using surface micromach	iining.	7
_	e short notes on material used for MEMS & Mi	2	7
	lain chemical sensors in MEMS.		7
b) Expl	lain optical transducer in MEMS.		6
	OR		\sim
6. a) Wha	at are different types of Thermal transducer in N	IEMS.	A ROL
50)	lain RF transducers in MEMS.		
· · · · ·	lain MEMS Inductor in detail.	~58	7
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OR

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8. a) Explain MEMS antennas.

11.

- b) Explain MEMS capacitors in detail.
- 9. a) Explain the types of MEMS packages.
 - b) Explain the MEMS wafer-level packaging.

OR

- **10.** a) Explain the importance of MEMS packaging.
 - b) Explain the flip-chip assembly in MEMS.
 - a) Explain typical system-on-chip (SoC) architecture.
 - b) Explain applications of microsystems.

12. a) Explain microsystems design methodology.

b) Give introduction to core architectures for digital media & the associated compilation techniques.

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OR

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